

IN THE CLAIMS:

Please substitute the following claims for the same-numbered claims in the application:

1. (Currently Amended) An integrated circuit structure comprising:
 - a carrier;
 - a device connected to said carrier;
 - solder connectors electrically connecting said device to said carrier;
 - a compressible film surrounding sides of said solder connectors, ~~wherein said compressible film has sufficient compressibility to accommodate expansion of said solder connectors when said solder connectors are melted without damaging said insulating material,~~ wherein said compressible film is stable above the melting point of said solder connectors, and wherein said compressible film remains compressible through more than one thermal excursion; and
 - an insulating material surrounding said compressible film and filling gaps between said carrier and said device,
 - wherein said compressible film has sufficient compressibility to accommodate expansion of said solder connectors when said solder connectors are melted without damaging said insulating material, and
 - wherein said compressible film is between said solder connectors and said insulating material.
- 2-3. (Cancelled).

4. (Original) The structure in claim 1, wherein said compressible film forms a pattern between said carrier and said device.
5. (Original) The structure in claim 4, wherein said pattern has channels between said device and said carrier, wherein said channels are filled with said insulating material.
6. (Original) The structure in claim 4, wherein said pattern comprises diagonal stripes of said compressible film.
7. (Original) The structure in claim 4, wherein said pattern comprises rectangles of said compressible film.
8. (Currently Amended) An integrated circuit structure comprising:
 - a carrier;
 - a device connected to said carrier;
 - lead-free connectors electrically connecting said device to said carrier;
 - a compressible film surrounding sides of said lead-free connectors, ~~wherein said compressible film has sufficient compressibility to accommodate up to a 3% volume expansion of said lead free connectors when said lead free connectors are melted without damaging said underfill~~, wherein said compressible film is stable above the melting point of said ~~solder~~ lead-free connectors, and wherein said compressible film remains compressible through more than one thermal excursion; and

an insulating underfill surrounding said compressible film and filling gaps between said carrier and said device,

wherein said compressible film has sufficient compressibility to accommodate up to a 3% volume expansion of said lead-free connectors when said lead-free connectors are melted without damaging said underfill, and

wherein said compressible film is between said lead-free connectors and said insulating underfill.

9-10. (Cancelled).

11. (Original) The structure in claim 8, wherein said compressible film forms a pattern between said carrier and said device.

12. (Original) The structure in claim 11, wherein said pattern has channels between said device and said carrier, wherein said channels are filled with said underfill.

13. (Original) The structure in claim 11, wherein said pattern comprises diagonal stripes of said compressible film.

14. (Original) The structure in claim 11, wherein said pattern comprises rectangles of said compressible film.

15-28. (Canceled).

29. (Currently Amended) An integrated circuit structure comprising:

- a carrier;
- a device connected to said carrier;
- solder connectors electrically connecting said device to said carrier;
- a compressible film comprising one of a rubber and a foam surrounding sides of said solder connectors, wherein said compressible film is stable above the melting point of said solder connectors, and wherein said compressible film remains compressible through more than one thermal excursion; and
- an insulating material surrounding said compressible film and filling gaps between said carrier and said device,

wherein said compressible film is between said solder connectors and said insulating material.

30. (Cancelled).

31. (Previously Presented) The structure in claim 29, wherein said compressible film has sufficient compressibility to accommodate expansion of said solder connectors when said solder connectors are melted without damaging said insulating material.

32. (Previously Presented) The structure in claim 29, wherein said compressible film forms a pattern between said carrier and said device.

33. (Previously Presented) The structure in claim 32, wherein said pattern has channels between said device and said carrier, wherein said channels are filled with said insulating material.

34. (Previously Presented) The structure in claim 32, wherein said pattern comprises diagonal stripes of said compressible film.

35. (Previously Presented) The structure in claim 32, wherein said pattern comprises rectangles of said compressible film.

36. (Previously Presented) The structure of claim 31, wherein said compressible film has sufficient compressibility to accommodate up to a 3% volume expansion of said solder connectors when said solder connectors are melted without damaging said insulating material.

37. (Previously Presented) The structure of claim 1, wherein said compressible film has sufficient compressibility to accommodate up to a 3% volume expansion of said solder connectors when said solder connectors are melted without damaging said insulating material.

38. (Previously Presented) The structure of claim 1, wherein said compressible film is distinct from said insulating material.

39. (Previously Presented) The structure of claim 8, wherein said compressible film is distinct from said insulating underfill.

40. (Previously Presented) The structure of claim 29, wherein said compressible film is distinct from said insulating material.